



Customer Information Notification

201706016I

Issue Date: 05-Aug-2017

Effective Date: 02-Nov-2017

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online



QUALITY

Management Summary

ESD max and Vcc min value change

Change Category

☐ Wafer Fab Process	☐ Assembly Process	☐ Product Marking	☐ Test Location	☐ Design
☐ Wafer Fab Materials	☐ Assembly Materials	☐ Mechanical Specification	☐ Test Process	☐ Errata
☐ Wafer Fab Location	☐ Assembly Location	☐ Packing/Shipping/Labeling	☐ Test Equipment	☒ Electrical spec./Test coverage

BGU805x
(BTS1001x): Updated
Data Sheet

Information Notification

Below changes are modified :

- the maximum value of VESD has been increased from 0.9 kV into 1.5 kV
- recommended operating conditions: the minimum value of VCC has been changed from 4.75 V into 3.3 V

Why do we issue this Information Notification

Change max specs for ESD and min spec for recommended operating conditions Vcc

Identification of Affected Products

No change in form, fit and function.

Impact

no impact to the product's functionality anticipated.

Data Sheet Revision

A new datasheet will be issued

Remarks

No change in form, fit and function. Datasheet already published on the internet.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Wali Ahmad
Position Sr. Customer Quality Engineer
e-mail address wali.ahmad@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

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Changed Orderable Part#	Changed Part 12NC	Changed Part Number	Changed Part Description	Package Outline	Package Name	Status	Product Line
BGU8052X	935298611115	BGU8052	Low Noise amp for wireless infra	SOT1327-1	HWS0N8	RFS	BL Smart Antenna Solutions